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FIG. 1

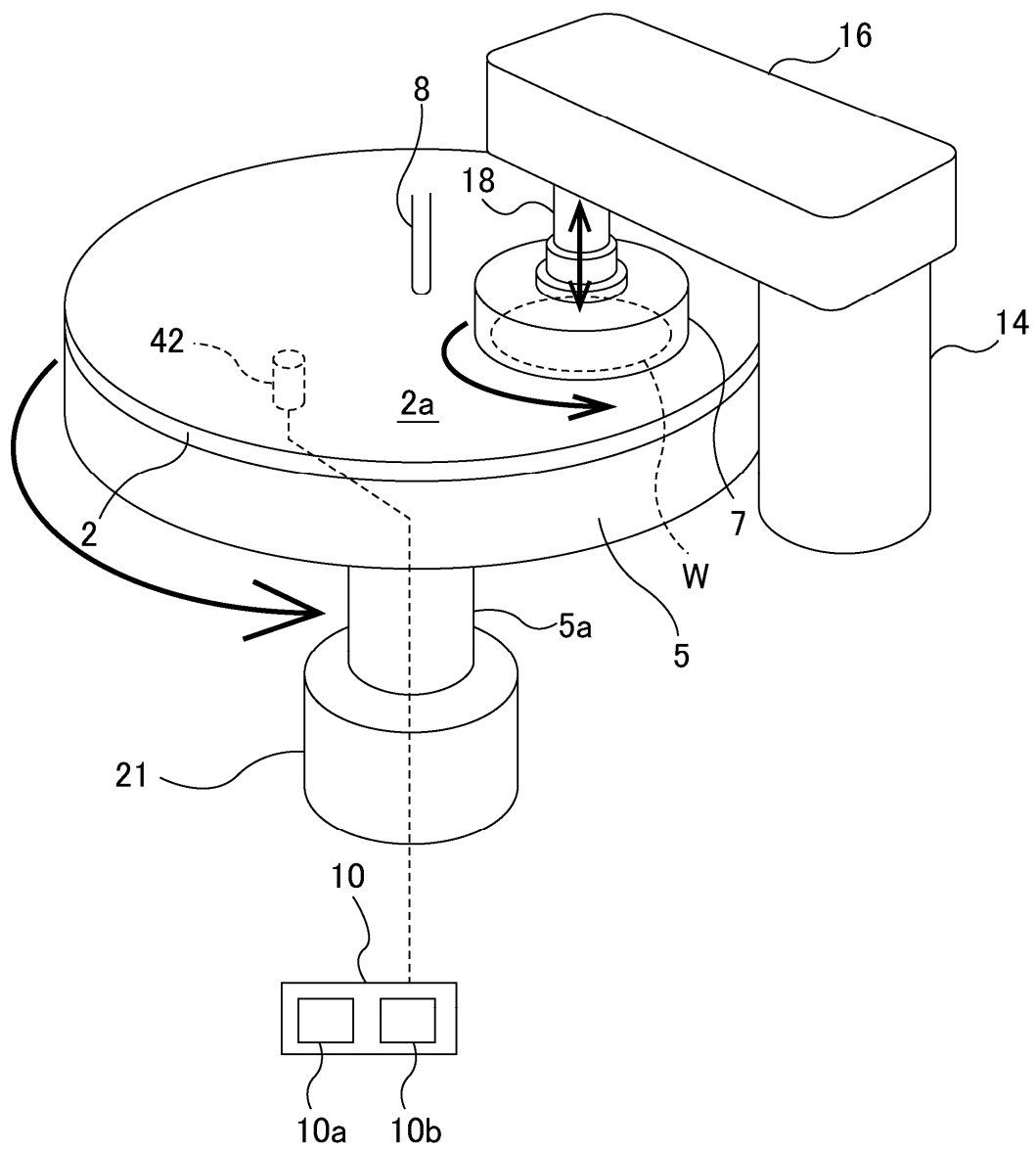


FIG. 2

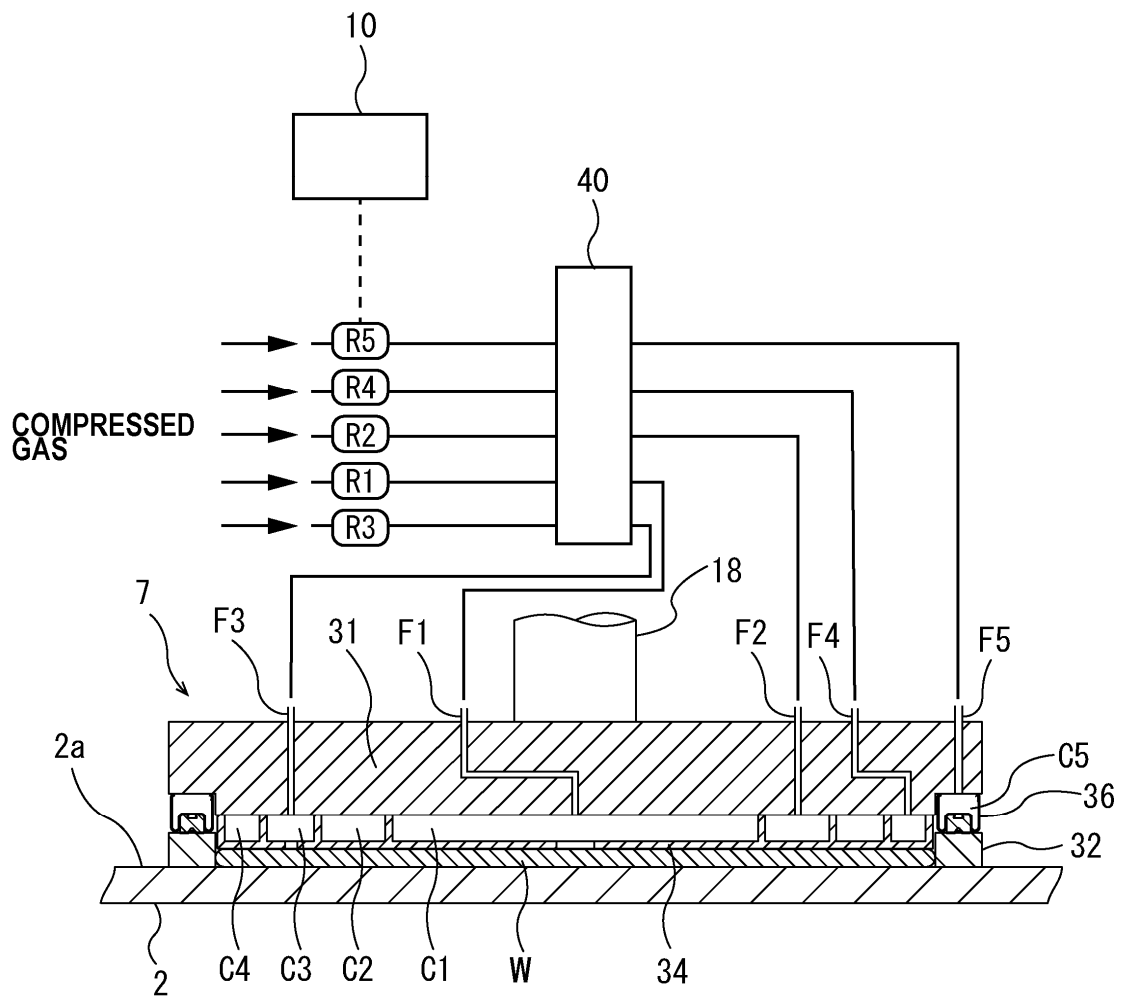


FIG. 3

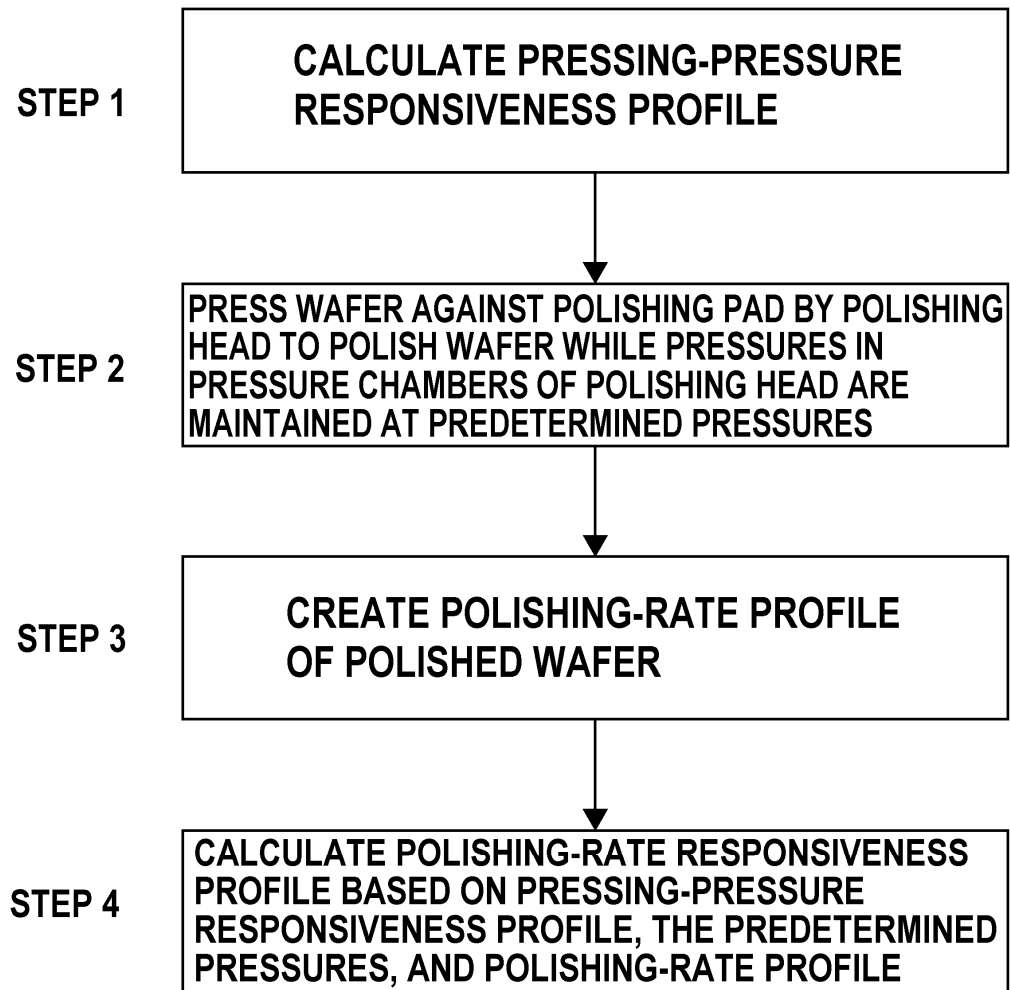


FIG. 4

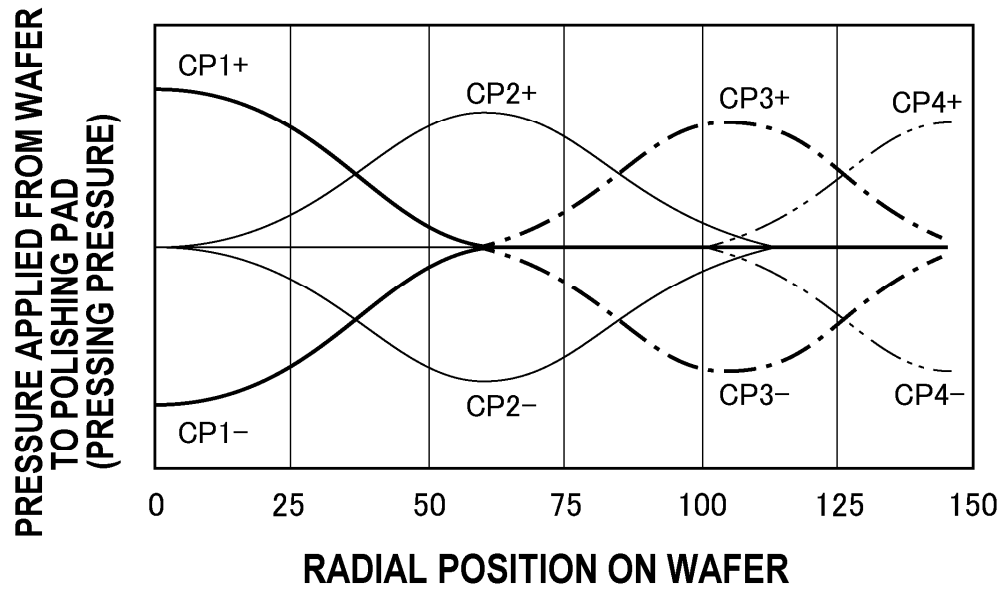


FIG. 5

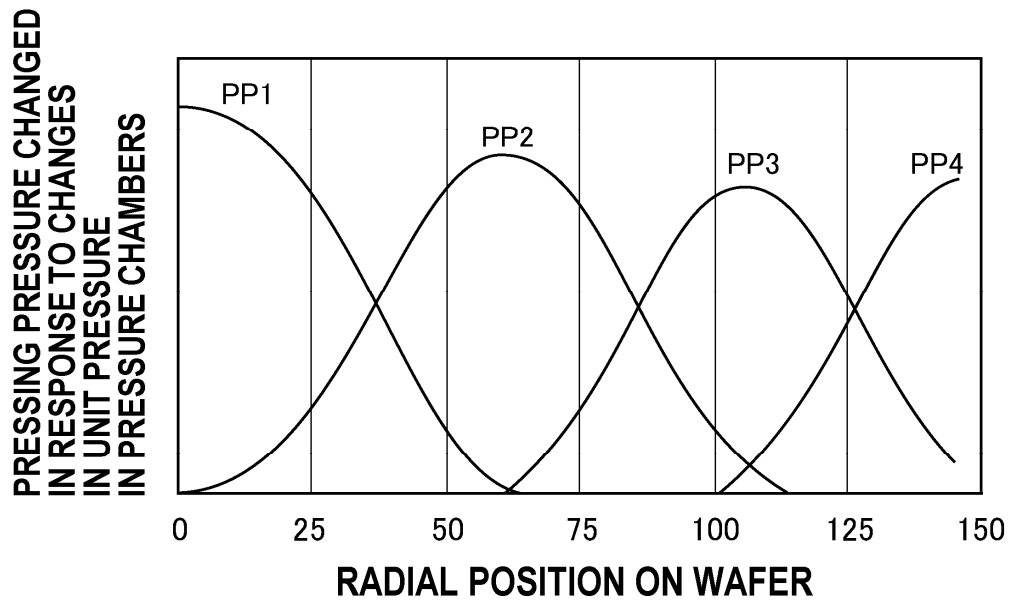


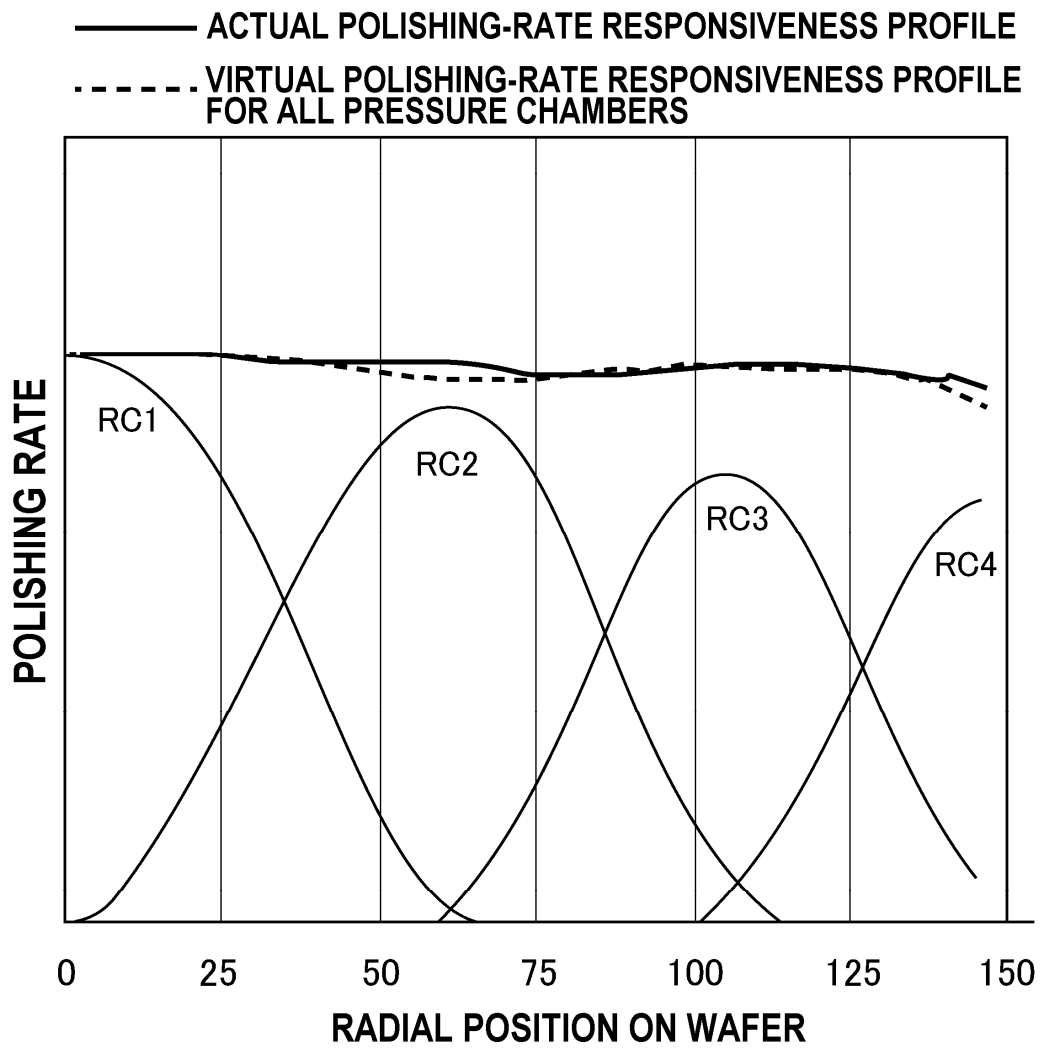
FIG. 6

FIG. 7**STEP 1**

CALCULATE PRESSING-PRESSURE
RESPONSIVENESS PROFILE

STEP 2

PRESS WAFER AGAINST POLISHING PAD BY POLISHING
HEAD TO POLISH WAFER WHILE PRESSURES IN
PRESSURE CHAMBERS OF POLISHING HEAD ARE
MAINTAINED AT PREDETERMINED PRESSURES

STEP 3

CREATE POLISHING-RATE PROFILE
OF POLISHED WAFER

STEP 4

CALCULATE POLISHING-RATE RESPONSIVENESS
PROFILE BASED ON PRESSING-PRESSURE
RESPONSIVENESS PROFILE, THE PREDETERMINED
PRESSURES, AND POLISHING-RATE PROFILE

STEP 5

OPTIMIZE POLISHING CONDITIONS
FOR NEXT WAFER

STEP 6

POLISH NEXT WAFER, AND CREATE
NEW POLISHING-RATE PROFILE

STEP 7

IS UPDATE CONDITION
OF POLISHING-RATE
COEFFICIENT SATISFIED?

NO

STEP 8

CALCULATE NEW POLISHING-RATE RESPONSIVENESS
PROFILE BASED ON PRESSING-PRESSURE
RESPONSIVENESS PROFILE, OPTIMIZED PREDETERMINED
PRESSURES, AND NEW POLISHING-RATE PROFILE

YES

